

L Number	Hits	Search Text	DB	Time stamp
1	1	("6114753").PN.	USPAT	2003/09/10 11:26
2	1	("6043109").PN.	USPAT	2003/09/10 11:28
3	3	"10027827"	JPO; DERWENT	2003/09/10 11:29
4	3	"2001102478"	JPO; DERWENT	2003/09/10 11:31
5	1	("6344401").PN.	USPAT	2003/09/10 11:34
6	1	"20010015009"	USPAT; US-PGPUB	2003/09/10 11:34
7	2012	(chip or die) and (solder adj (resist or mask)) and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 11:37
8	1486	((chip or die) and (solder adj (resist or mask)) and wire) and (ball or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 11:38
9	383	((chip or die) and (solder adj (resist or mask)) and wire) and (ball or bump)) and (@ad<19980211)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 11:38
10	285	((((chip or die) and (solder adj (resist or mask)) and wire) and (ball or bump)) and (@ad<19980211)) and (resin or potting or encapsulate or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 11:39
11	137	(((((chip or die) and (solder adj (resist or mask)) and wire) and (ball or bump)) and (@ad<19980211)) and (resin or potting or encapsulate or encapsulant)) and (dice or cut or saw or singulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 11:39